

Docket No. 10936-38

**CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on April 6, 2000.

Laureen E. Mains  
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**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

Applicant: Junji KODEMURA : Paper No.:  
Serial No.: 09/462,214 : Group Art Unit:  
Filing Date: January 4, 2000 : Examiner:

For: **Adhesive for Semiconductor Part**

**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner of Patents  
Washington, DC 20231

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56 and 1.97-1.98, Applicants cite and submit copies of the references listed on the attached Form PTO-1449. English language abstracts of the Japanese patent references are also enclosed. The relevance of the Japanese publication of the *Society for Hybrid Microelectronics* is set forth at page 36 of the present specification and is directed to the details of specific sealing methods as described in the application.

Since the present Statement is submitted prior to issuance of a first Official Action in this application, no statement or fee under 37 C.F.R. 1.97 is required.

Respectfully submitted,

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